CLAIMS

[Claim 1] A polishing liquid, comprising: abrasive grains containing cerium oxide and an ammonium salt, wherein

the ammonium salt includes at least one selected from the group consisting of ammonium chloride, ammonium carbonate, ammonium hydrogen carbonate, ammonium sulfate, ammonium dihydrogen phosphate, and ammonium acetate, and a pH is 9.00 or more.

[Claim 2] The polishing liquid according to claim 1, wherein the ammonium salt includes ammonium carbonate.

[Claim 3] The polishing liquid according to claim 2, wherein the ammonium salt further includes ammonium persulfate.

[Claim 4] The polishing liquid according to claim 1, wherein a content of the ammonium salt is 0.3 to 2% by mass.

[Claim 5] The polishing liquid according to claim 1, further comprising ammonia.

[Claim 6] The polishing liquid according to claim 1, further comprising an ether compound having a hydroxy group.

[Claim 7] The polishing liquid according to claim 6, wherein the ether compound includes an alkoxy alcohol.

[Claim 8] The polishing liquid according to claim 7, wherein the alkoxy alcohol includes 3-methoxy-3-methyl-1-butanol.

[Claim 9] The polishing liquid according to claim 7, wherein a content of the alkoxy alcohol is 0.2 to 0.8% by mass on the basis of the total mass of the polishing liquid.

[Claim 10] The polishing liquid according to claim 6, wherein the ether compound includes a compound having two or more hydroxy

groups.

[Claim 11] The polishing liquid according to claim 7, wherein the ether compound further includes a polyether.

[Claim 12] The polishing liquid according to claim 11, wherein the polyether includes polyglycerol.

[Claim 13] The polishing liquid according to claim 11, wherein a content of the polyether is 0.5 to 3% by mass on the basis of the total mass of the polishing liquid.

[Claim 14] The polishing liquid according to claim 1, wherein the pH is 9.00 to 11.00.

[Claim 15] A polishing method, comprising: polishing a member to be polished containing copper by using the polishing liquid according to any one of claims 1 to 14.

[Claim 16] A method for manufacturing a component, comprising: obtaining a component by using a polished member polished by the polishing method according to claim 15.

[Claim 17] A method for manufacturing a semiconductor component, comprising: obtaining a semiconductor component by using a polished member polished by the polishing method according to claim 15.